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#### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "[Embedded - Microcontrollers](#)"

##### Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	47
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b840f1024gq64-a">https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b840f1024gq64-a</a>

## 3.7 Security Features

### 3.7.1 GPCRC (General Purpose Cyclic Redundancy Check)

The GPCRC module implements a Cyclic Redundancy Check (CRC) function. It supports both 32-bit and 16-bit polynomials. The supported 32-bit polynomial is 0x04C11DB7 (IEEE 802.3), while the 16-bit polynomial can be programmed to any value, depending on the needs of the application.

### 3.7.2 Crypto Accelerator (CRYPTO)

The Crypto Accelerator is a fast and energy-efficient autonomous hardware encryption and decryption accelerator. Giant Gecko Series 1 devices support AES encryption and decryption with 128- or 256-bit keys, ECC over both GF(P) and GF( $2^m$ ), and SHA-1 and SHA-2 (SHA-224 and SHA-256).

Supported block cipher modes of operation for AES include: ECB, CTR, CBC, PCBC, CFB, OFB, GCM, CBC-MAC, GMAC and CCM.

Supported ECC NIST recommended curves include P-192, P-224, P-256, K-163, K-233, B-163 and B-233.

The CRYPTO module allows fast processing of GCM (AES), ECC and SHA with little CPU intervention. CRYPTO also provides trigger signals for DMA read and write operations.

### 3.7.3 True Random Number Generator (TRNG)

The TRNG module is a non-deterministic random number generator based on a full hardware solution. The TRNG is validated with NIST800-22 and AIS-31 test suites as well as being suitable for FIPS 140-2 certification (for the purposes of cryptographic key generation).

## 3.8 Analog

### 3.8.1 Analog Port (APORT)

The Analog Port (APORT) is an analog interconnect matrix allowing access to many analog modules on a flexible selection of pins. Each APORT bus consists of analog switches connected to a common wire. Since many clients can operate differentially, buses are grouped by X/Y pairs.

### 3.8.2 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs are selected from among internal references and external pins. The tradeoff between response time and current consumption is configurable by software. Two 6-bit reference dividers allow for a wide range of internally-programmable reference sources. The ACMP can also be used to monitor the supply voltage. An interrupt can be generated when the supply falls below or rises above the programmable threshold.

### 3.8.3 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to 1 Msps. The output sample resolution is configurable and additional resolution is possible using integrated hardware for averaging over multiple samples. The ADC includes integrated voltage references and an integrated temperature sensor. Inputs are selectable from a wide range of sources, including pins configurable as either single-ended or differential.

### 3.12 Configuration Summary

The features of the EFM32GG11 are a subset of the feature set described in the device reference manual. The table below describes device specific implementation of the features. Remaining modules support full configuration.

**Table 3.2. Configuration Summary**

Module	Configuration	Pin Connections
USART0	IrDA, SmartCard	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	I <sup>2</sup> S, SmartCard	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	IrDA, SmartCard, High-Speed	US2_TX, US2_RX, US2_CLK, US2_CS
USART3	I <sup>2</sup> S, SmartCard	US3_TX, US3_RX, US3_CLK, US3_CS
USART4	I <sup>2</sup> S, SmartCard	US4_TX, US4_RX, US4_CLK, US4_CS
USART5	SmartCard	US5_TX, US5_RX, US5_CLK, US5_CS
TIMER0	with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	-	TIM1_CC[3:0]
TIMER2	with DTI	TIM2_CC[2:0], TIM2_CDTI[2:0]
TIMER3	-	TIM3_CC[2:0]
TIMER4	with DTI	TIM4_CC[2:0], TIM4_CDTI[2:0]
TIMER5	-	TIM5_CC[2:0]
TIMER6	with DTI	TIM6_CC[2:0], TIM6_CDTI[2:0]
WTIMER0	with DTI	WTIM0_CC[2:0], WTIM0_CDTI[2:0]
WTIMER1	-	WTIM1_CC[3:0]
WTIMER2	-	WTIM2_CC[2:0]
WTIMER3	-	WTIM3_CC[2:0]

#### 4.1.4 DC-DC Converter

Test conditions: L\_DCDC=4.7  $\mu$ H (Murata LQH3NPN4R7MM0L), C\_DCDC=4.7  $\mu$ F (Samsung CL10B475KQ8NQNC), V\_DCDC\_I=3.3 V, V\_DCDC\_O=1.8 V, I\_DCDC\_LOAD=50 mA, Heavy Drive configuration, F\_DCDC\_LN=7 MHz, unless otherwise indicated.

**Table 4.4. DC-DC Converter**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V <sub>DCDC_I</sub>	Bypass mode, I <sub>DCDC_LOAD</sub> = 50 mA	1.8	—	V <sub>VREGVDD_MAX</sub>	V
		Low noise (LN) mode, 1.8 V output, I <sub>DCDC_LOAD</sub> = 100 mA, or Low power (LP) mode, 1.8 V output, I <sub>DCDC_LOAD</sub> = 10 mA	2.4	—	V <sub>VREGVDD_MAX</sub>	V
		Low noise (LN) mode, 1.8 V output, I <sub>DCDC_LOAD</sub> = 200 mA	2.6	—	V <sub>VREGVDD_MAX</sub>	V
Output voltage programmable range <sup>1</sup>	V <sub>DCDC_O</sub>		1.8	—	V <sub>VREGVDD</sub>	V
Regulation DC accuracy	ACC <sub>DC</sub>	Low Noise (LN) mode, 1.8 V target output	TBD	—	TBD	V
Regulation window <sup>4</sup>	WIN <sub>REG</sub>	Low Power (LP) mode, LPCMPBIASEMxx <sup>3</sup> = 0, 1.8 V target output, I <sub>DCDC_LOAD</sub> $\leq$ 75 $\mu$ A	TBD	—	TBD	V
		Low Power (LP) mode, LPCMPBIASEMxx <sup>3</sup> = 3, 1.8 V target output, I <sub>DCDC_LOAD</sub> $\leq$ 10 mA	TBD	—	TBD	V
Steady-state output ripple	V <sub>R</sub>		—	3	—	mVpp
Output voltage under/overshoot	V <sub>Ov</sub>	CCM Mode (LNFORCECCM <sup>3</sup> = 1), Load changes between 0 mA and 100 mA	—	25	TBD	mV
		DCM Mode (LNFORCECCM <sup>3</sup> = 0), Load changes between 0 mA and 10 mA	—	45	TBD	mV
		Overshoot during LP to LN CCM/DCM mode transitions compared to DC level in LN mode	—	200	—	mV
		Undershoot during BYP/LP to LN CCM (LNFORCECCM <sup>3</sup> = 1) mode transitions compared to DC level in LN mode	—	40	—	mV
		Undershoot during BYP/LP to LN DCM (LNFORCECCM <sup>3</sup> = 0) mode transitions compared to DC level in LN mode	—	100	—	mV
DC line regulation	V <sub>REG</sub>	Input changes between V <sub>VREGVDD_MAX</sub> and 2.4 V	—	0.1	—	%
DC load regulation	I <sub>REG</sub>	Load changes between 0 mA and 100 mA in CCM mode	—	0.1	—	%

**4.1.5 5V Regulator**

$V_{VREGI} = 5\text{ V}$ ,  $V_{VREGO} = 3.3\text{ V}$ ,  $C_{VREGI} = 10\text{ }\mu\text{F}$ ,  $C_{VREGO} = 4.7\text{ }\mu\text{F}$ , unless otherwise specified.

**Table 4.5. 5V Regulator**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
VREGI or VBUS input voltage range	$V_{VREGI}$	Regulating output	2.7	—	5.5	V
		Bypass mode enabled	2.7	—	3.8	V
VREGO output voltage	$V_{VREGO}$	Regulating output, 3.3 V setting	3.1	3.3	3.5	V
		EM4S open-loop output, $I_{OUT} < 100\text{ }\mu\text{A}$	1.8	—	3.8	V
Voltage output step size	$V_{VREGO\_SS}$		—	0.1	—	V
Resistance in Bypass Mode	$R_{BYP}$	Bypass mode enabled	—	1.2	TBD	$\Omega$
Output current	$I_{OUT}$	EM0 or EM1, $V_{VREGI} > V_{VREGO} + 0.6\text{ V}$	—	—	200	mA
		EM0 or EM1, $V_{VREGI} > V_{VREGO} + 0.3\text{ V}$	—	—	100	mA
		EM2, EM3, or EM4H, $V_{VREGI} > V_{VREGO} + 0.6\text{ V}$	—	—	2	mA
		EM2, EM3, or EM4H, $V_{VREGI} > V_{VREGO} + 0.3\text{ V}$	—	—	0.5	mA
		EM4S	—	—	20	$\mu\text{A}$
Load regulation	$L_{R_{VREGO}}$	EM0 or EM1	—	0.10	—	$\text{mV/mA}$
		EM2, EM3, or EM4H	—	2.5	—	$\text{mV/mA}$
DC power supply rejection	$PSR_{DC}$		—	40	—	dB
VREGI or VBUS bypass capacitance	$C_{VREGI}$		—	10	—	$\mu\text{F}$
VREGO bypass capacitance	$C_{VREGO}$		1	4.7	10	$\mu\text{F}$
Supply current consumption	$I_{VREGI}$	EM0 or EM1, No load	—	29	—	$\mu\text{A}$
		EM2, EM3, or EM4H, No load	—	270	—	nA
		EM4S, No load	—	70	—	nA
VREGI and VBUS detection high threshold	$V_{DET\_H}$		TBD	1.18	—	V
VREGI and VBUS detection low threshold	$V_{DET\_L}$		—	1.12	TBD	V
Current monitor transfer ratio	$IMON_{XF}$	Translation of current through VREGO path to voltage at ADC input	—	0.35	—	$\text{mA/mV}$

**4.1.16 Digital to Analog Converter (VDAC)**

DRIVESTRENGTH = 2 unless otherwise specified. Primary VDAC output.

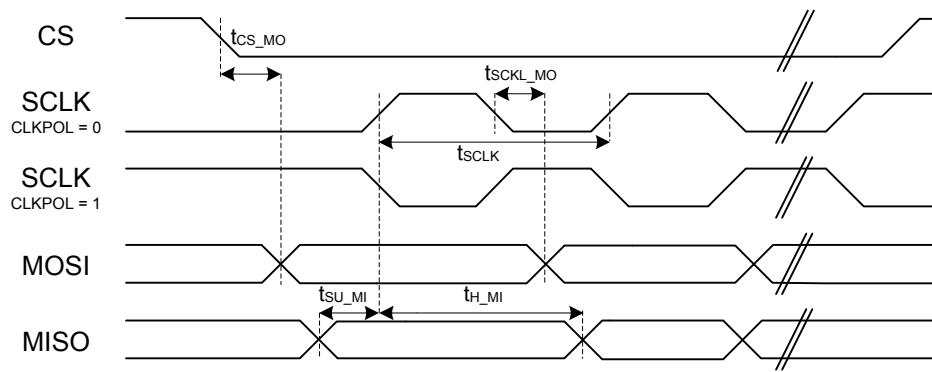
**Table 4.24. Digital to Analog Converter (VDAC)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output voltage	V <sub>DACOUT</sub>	Single-Ended	0	—	V <sub>VREF</sub>	V
		Differential <sup>2</sup>	-V <sub>VREF</sub>	—	V <sub>VREF</sub>	V
Current consumption including references (2 channels) <sup>1</sup>	I <sub>DAC</sub>	500 ksps, 12-bit, DRIVESTRENGTH = 2, REFSEL = 4	—	402	—	μA
		44.1 ksps, 12-bit, DRIVESTRENGTH = 1, REFSEL = 4	—	88	—	μA
		200 Hz refresh rate, 12-bit Sample-Off mode in EM2, DRIVESTRENGTH = 2, BGRREQTIME = 1, EM2REFENTIME = 9, REFSEL = 4, SETTLETIME = 0x0A, WARMUPTIME = 0x02	—	2	—	μA
Current from HPERCLK <sup>4</sup>	I <sub>DAC_CLK</sub>		—	5.25	—	μA/MHz
Sample rate	S <sub>R</sub> <sub>DAC</sub>		—	—	500	ksps
DAC clock frequency	f <sub>DAC</sub>		—	—	1	MHz
Conversion time	t <sub>DACCONV</sub>	f <sub>DAC</sub> = 1MHz	2	—	—	μs
Settling time	t <sub>DACSETTLE</sub>	50% fs step settling to 5 LSB	—	2.5	—	μs
Startup time	t <sub>DACSTARTUP</sub>	Enable to 90% fs output, settling to 10 LSB	—	—	12	μs
Output impedance	R <sub>OUT</sub>	DRIVESTRENGTH = 2, 0.4 V ≤ V <sub>OUT</sub> ≤ V <sub>OPA</sub> - 0.4 V, -8 mA < I <sub>OUT</sub> < 8 mA, Full supply range	—	2	—	Ω
		DRIVESTRENGTH = 0 or 1, 0.4 V ≤ V <sub>OUT</sub> ≤ V <sub>OPA</sub> - 0.4 V, -400 μA < I <sub>OUT</sub> < 400 μA, Full supply range	—	2	—	Ω
		DRIVESTRENGTH = 2, 0.1 V ≤ V <sub>OUT</sub> ≤ V <sub>OPA</sub> - 0.1 V, -2 mA < I <sub>OUT</sub> < 2 mA, Full supply range	—	2	—	Ω
		DRIVESTRENGTH = 0 or 1, 0.1 V ≤ V <sub>OUT</sub> ≤ V <sub>OPA</sub> - 0.1 V, -100 μA < I <sub>OUT</sub> < 100 μA, Full supply range	—	2	—	Ω
Power supply rejection ratio <sup>6</sup>	PSRR	Vout = 50% fs. DC	—	65.5	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
MISO hold time <sup>1 3</sup>	$t_{H\_MI}$	USART2, location 4, IOVDD = 1.8 V	-11.6	—	—	ns
		USART2, location 4, IOVDD = 3.0 V	-11.6	—	—	ns
		USART2, location 5, IOVDD = 1.8 V	-9.1	—	—	ns
		USART2, location 5, IOVDD = 3.0 V	-9.1	—	—	ns
		All other USARTs and locations, IOVDD = 1.8 V	-8	—	—	ns
		All other USARTs and locations, IOVDD = 3.0 V	-8	—	—	ns

**Note:**

1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0).
2.  $t_{HPERCLK}$  is one period of the selected HPERCLK.
3. Measurement done with 8 pF output loading at 10% and 90% of  $V_{DD}$  (figure shows 50% of  $V_{DD}$ ).

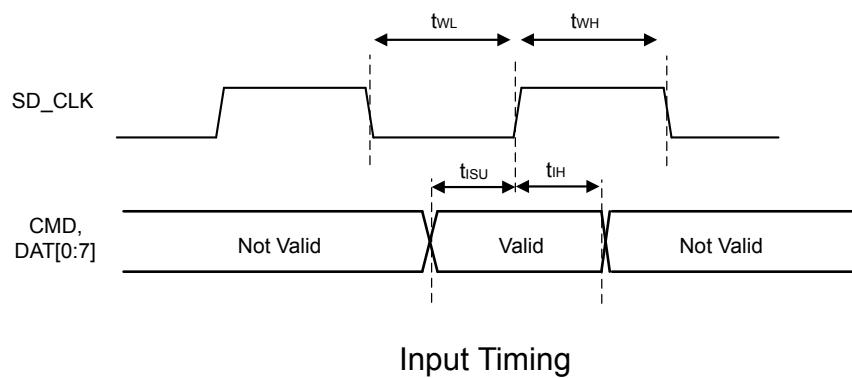
**Figure 4.1. SPI Master Timing Diagram**

**SDIO MMC SDR Mode Timing at 1.8 V**

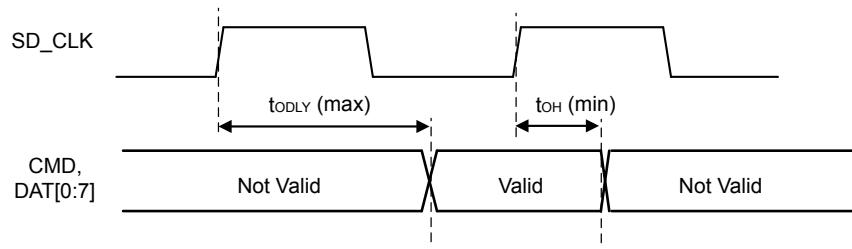
Timing is specified for route location 0 at 1.8 V IOVDD with voltage scaling disabled. Slew rate for SD\_CLK set to 7, all other GPIO set to 6, DRIVESTRENGTH = STRONG for all pins. SDIO\_CTRL\_TXDLYMUXSEL = 1. Loading between 5 and 10 pF on all pins or between 10 and 20 pF on all pins.

**Table 4.50. SDIO MMC SDR Mode Timing (Location 0, 1.8V I/O)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Clock frequency during data transfer	FSD_CLK	Using HFRCO, AUXHFRCO, or USHFRCO	—	—	25	MHz
		Using HFXO	—	—	TBD	MHz
Clock low time	tWL	Using HFRCO, AUXHFRCO, or USHFRCO	18.1	—	—	ns
		Using HFXO	TBD	—	—	ns
Clock high time	tWH	Using HFRCO, AUXHFRCO, or USHFRCO	18.1	—	—	ns
		Using HFXO	TBD	—	—	ns
Clock rise time	tR		1.96	8.27	—	ns
Clock fall time	tF		1.67	6.90	—	ns
Input setup time, CMD, DAT[0:7] valid to SD_CLK	tISU		5.3	—	—	ns
Input hold time, SD_CLK to CMD, DAT[0:7] change	tIH		2.5	—	—	ns
Output delay time, SD_CLK to CMD, DAT[0:7] valid	tODLY		0	—	16	ns
Output hold time, SD_CLK to CMD, DAT[0:7] change	tOH		3	—	—	ns



Input Timing



Output Timing

Figure 4.18. SDIO MMC SDR Mode Timing

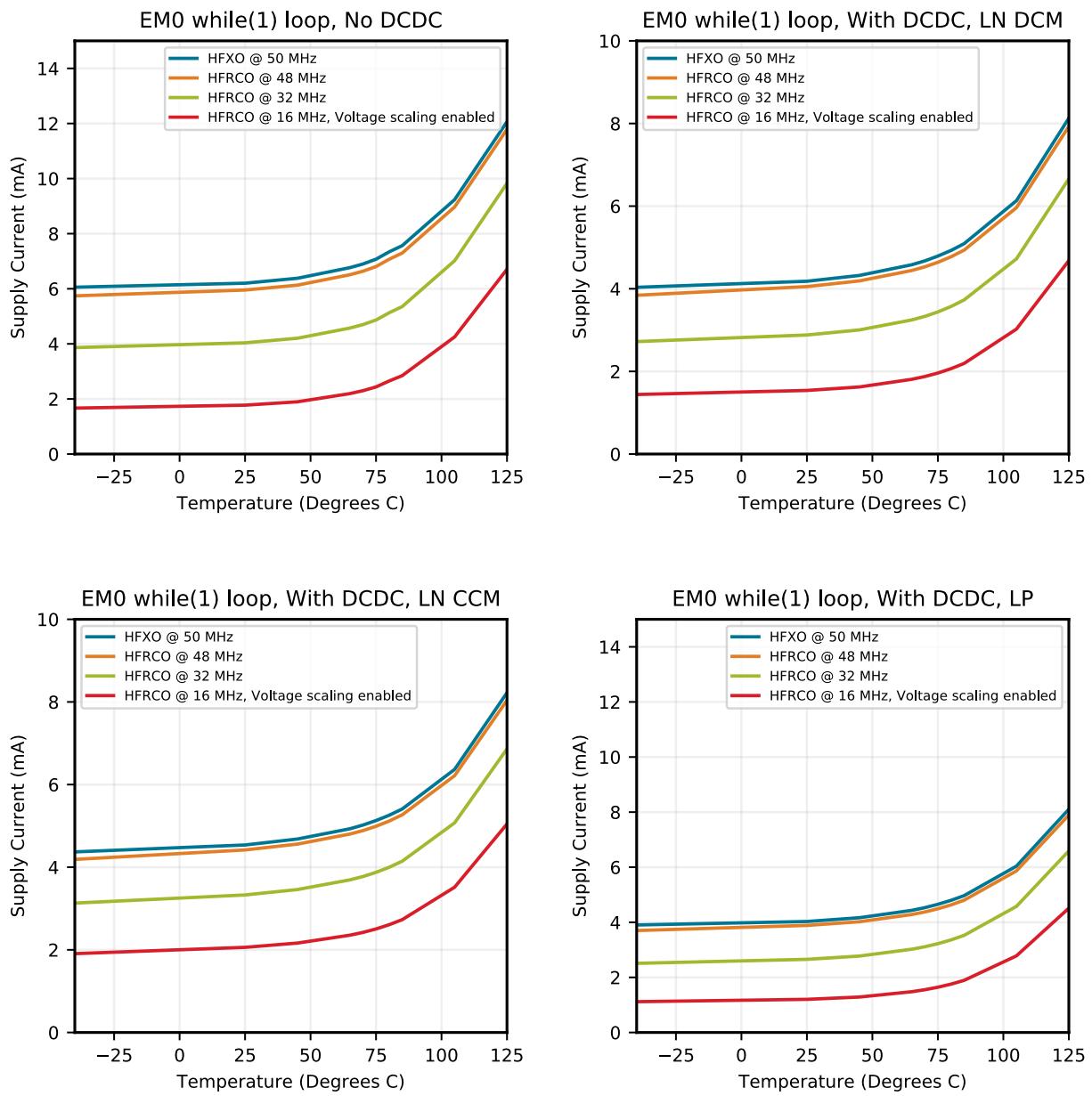
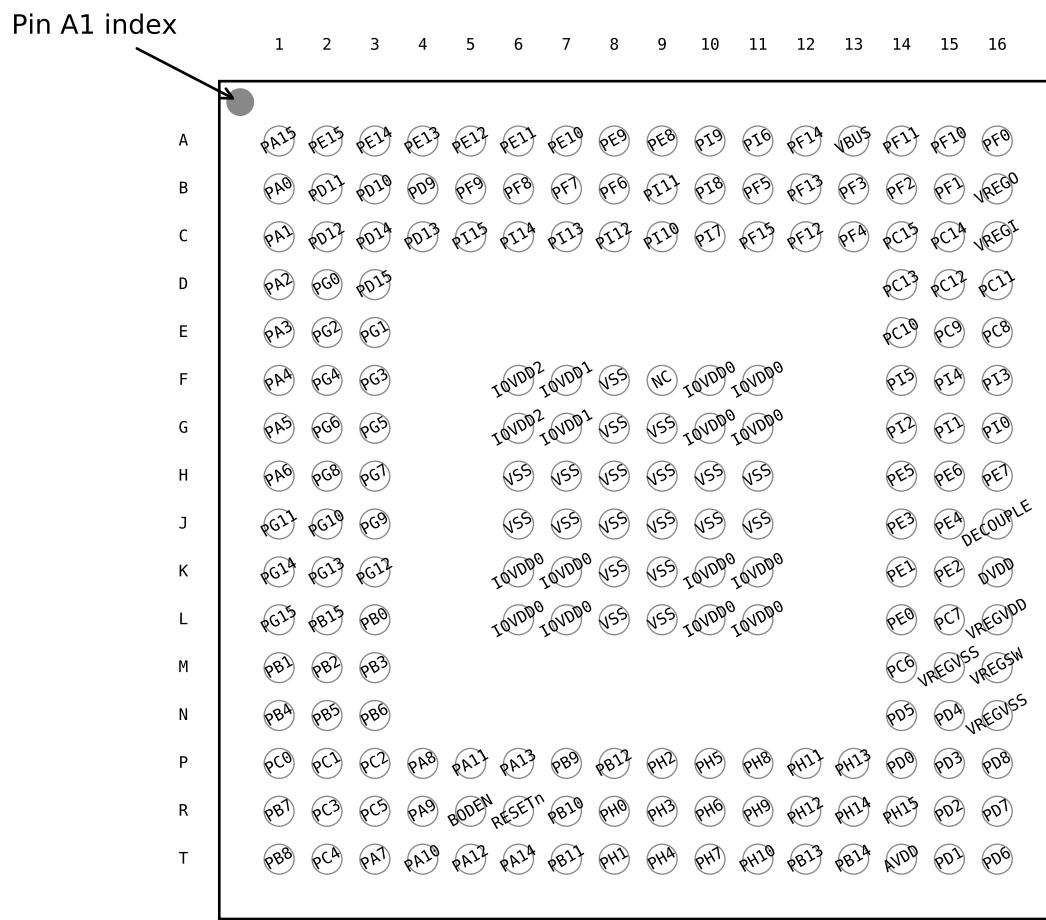


Figure 4.24. EM0 Active Mode Typical Supply Current vs. Temperature

## 5. Pin Definitions

### 5.1 EFM32GG11B8xx in BGA192 Device Pinout



**Figure 5.1. EFM32GG11B8xx in BGA192 Device Pinout**

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

**Table 5.1. EFM32GG11B8xx in BGA192 Device Pinout**

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA15	A1	GPIO	PE15	A2	GPIO
PE14	A3	GPIO	PE13	A4	GPIO
PE12	A5	GPIO	PE11	A6	GPIO
PE10	A7	GPIO	PE9	A8	GPIO
PE8	A9	GPIO	PI9	A10	GPIO (5V)
PI6	A11	GPIO (5V)	PF14	A12	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
<b>Note:</b>					
1.	GPIO with 5V tolerance are indicated by (5V).				

## 5.4 EFM32GG11B5xx in BGA120 Device Pinout

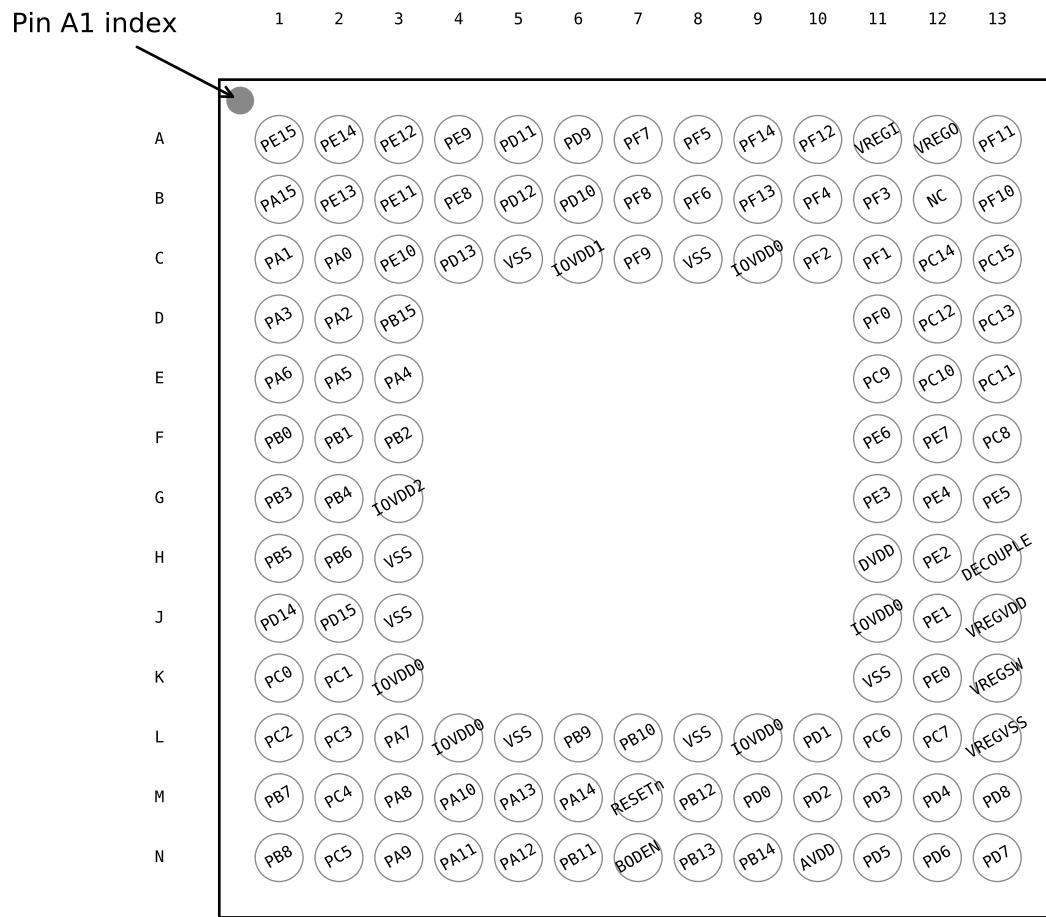


Figure 5.4. EFM32GG11B5xx in BGA120 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.4. EFM32GG11B5xx in BGA120 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PE15	A1	GPIO	PE14	A2	GPIO
PE12	A3	GPIO	PE9	A4	GPIO
PD11	A5	GPIO	PD9	A6	GPIO
PF7	A7	GPIO	PF5	A8	GPIO
PF14	A9	GPIO (5V)	PF12	A10	GPIO
VREGI	A11	Input to 5 V regulator.	VREGO	A12	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PF11	A13	GPIO (5V)	PA15	B1	GPIO
PE13	B2	GPIO	PE11	B3	GPIO
PE8	B4	GPIO	PD12	B5	GPIO
PD10	B6	GPIO	PF8	B7	GPIO
PF6	B8	GPIO	PF13	B9	GPIO (5V)
PF4	B10	GPIO	PF3	B11	GPIO
NC	B12	No Connect.	PF10	B13	GPIO (5V)
PA1	C1	GPIO	PA0	C2	GPIO
PE10	C3	GPIO	PD13	C4	GPIO (5V)
VSS	C5 C8 H3 J3 K11 L12 L15	Ground	IOVDD1	C6	Digital IO power supply 1.
PF9	C7	GPIO	IOVDD0	C9 J11 K3 L11 L16	Digital IO power supply 0.
PF2	C10	GPIO	PF1	C11	GPIO (5V)
PC14	C12	GPIO (5V)	PC15	C13	GPIO (5V)
PA3	D1	GPIO	PA2	D2	GPIO
PB15	D3	GPIO (5V)	PF0	D11	GPIO (5V)
PC12	D12	GPIO (5V)	PC13	D13	GPIO (5V)
PA6	E1	GPIO	PA5	E2	GPIO
PA4	E3	GPIO	PC9	E11	GPIO (5V)
PC10	E12	GPIO (5V)	PC11	E13	GPIO (5V)
PB0	F1	GPIO	PB1	F2	GPIO
PB2	F3	GPIO	PE6	F11	GPIO
PE7	F12	GPIO	PC8	F13	GPIO (5V)
PB3	G1	GPIO	PB4	G2	GPIO
IOVDD2	G3	Digital IO power supply 2.	PE3	G11	GPIO
PE4	G12	GPIO	PE5	G13	GPIO
PB5	H1	GPIO	PB6	H2	GPIO
DVDD	H11	Digital power supply.	PE2	H12	GPIO
DECOPPLE	H13	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PD14	J1	GPIO (5V)
PD15	J2	GPIO (5V)	PE1	J12	GPIO (5V)
VREGVDD	J13	Voltage regulator VDD input	PC0	K1	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC1	K2	GPIO (5V)	PE0	K12	GPIO (5V)
VREGSW	K13	DCDC regulator switching node	PC2	L1	GPIO (5V)
PC3	L2	GPIO (5V)	PA7	L3	GPIO
PB9	L13	GPIO (5V)	PB10	L14	GPIO (5V)
PD1	L17	GPIO	PC6	L18	GPIO
PC7	L19	GPIO	VREGVSS	L20	Voltage regulator VSS
PB7	M1	GPIO	PC4	M2	GPIO
PA8	M3	GPIO	PA10	M4	GPIO
PA13	M5	GPIO (5V)	PA14	M6	GPIO
RESETn	M7	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB12	M8	GPIO
PD0	M9	GPIO (5V)	PD2	M10	GPIO (5V)
PD3	M11	GPIO	PD4	M12	GPIO
PD8	M13	GPIO	PB8	N1	GPIO
PC5	N2	GPIO	PA9	N3	GPIO
PA11	N4	GPIO	PA12	N5	GPIO (5V)
PB11	N6	GPIO	BODEN	N7	Brown-Out Detector Enable. This pin may be left disconnected or tied to AVDD.
PB13	N8	GPIO	PB14	N9	GPIO
AVDD	N10	Analog power supply.	PD5	N11	GPIO
PD6	N12	GPIO	PD7	N13	GPIO

**Note:**

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

## 5.14 EFM32GG11B4xx in QFP64 Device Pinout

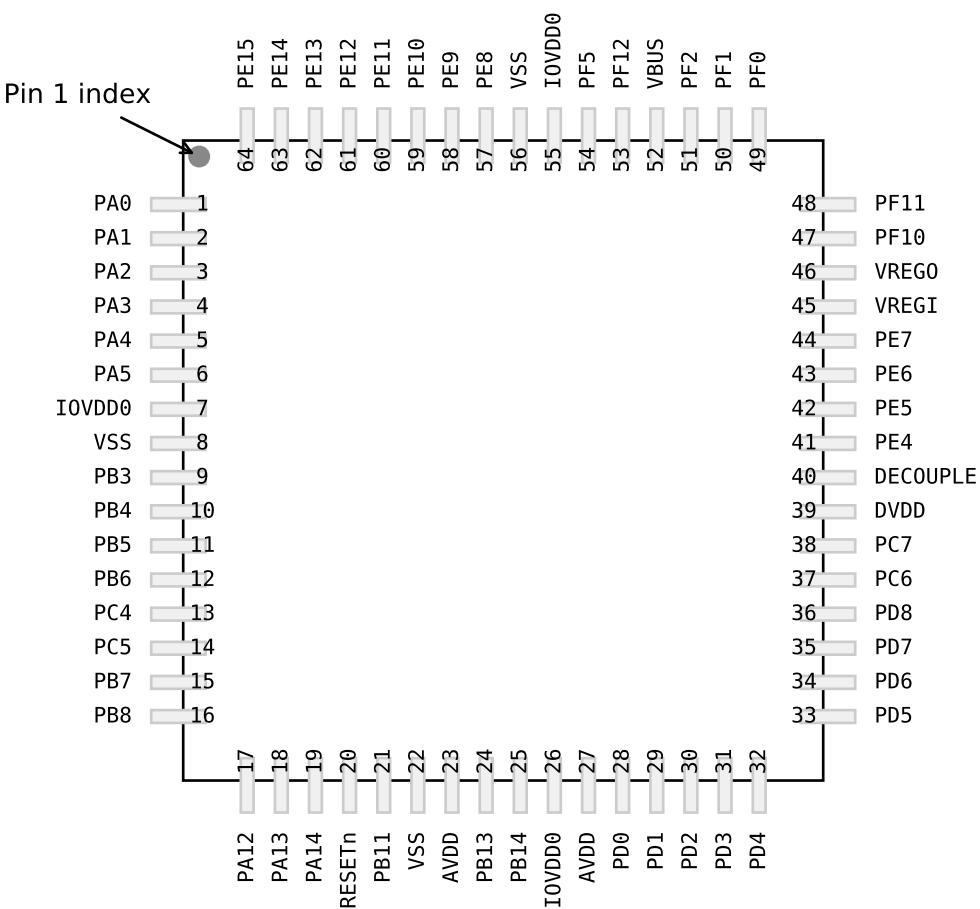


Figure 5.14. EFM32GG11B4xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.14. EFM32GG11B4xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 26 55	Digital IO power supply 0.	VSS	8 22 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

## 5.19 EFM32GG11B1xx in QFN64 Device Pinout

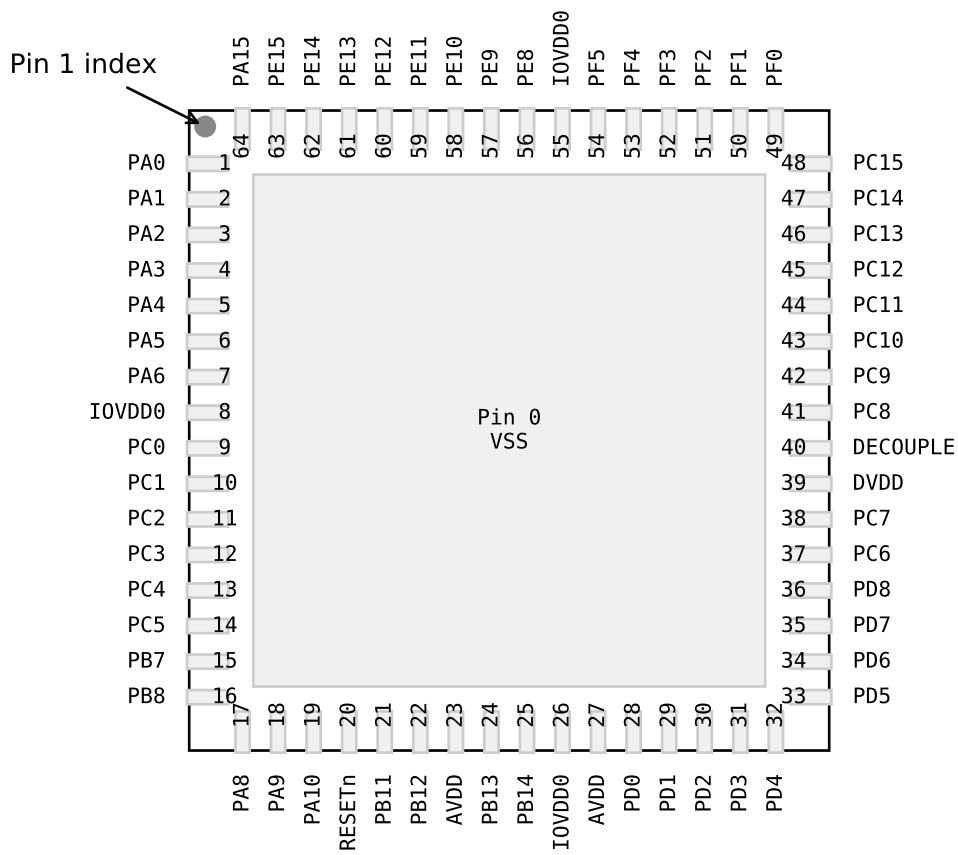


Figure 5.19. EFM32GG11B1xx in QFN64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.19. EFM32GG11B1xx in QFN64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
VSS	0	Ground	PA0	1	GPIO
PA1	2	GPIO	PA2	3	GPIO
PA3	4	GPIO	PA4	5	GPIO
PA5	6	GPIO	PA6	7	GPIO
IOVDD0	8 26 55	Digital IO power supply 0.	PC0	9	GPIO (5V)
PC1	10	GPIO (5V)	PC2	11	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC3	12	GPIO (5V)	PC4	13	GPIO
PC5	14	GPIO	PB7	15	GPIO
PB8	16	GPIO	PA8	17	GPIO
PA9	18	GPIO	PA10	19	GPIO
RESETn	20	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB11	21	GPIO
PB12	22	GPIO	AVDD	23 27	Analog power supply.
PB13	24	GPIO	PB14	25	GPIO
PD0	28	GPIO (5V)	PD1	29	GPIO
PD2	30	GPIO (5V)	PD3	31	GPIO
PD4	32	GPIO	PD5	33	GPIO
PD6	34	GPIO	PD7	35	GPIO
PD8	36	GPIO	PC6	37	GPIO
PC7	38	GPIO	DVDD	39	Digital power supply.
DECOPUPLE	40	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PC8	41	GPIO (5V)
PC9	42	GPIO (5V)	PC10	43	GPIO (5V)
PC11	44	GPIO (5V)	PC12	45	GPIO (5V)
PC13	46	GPIO (5V)	PC14	47	GPIO (5V)
PC15	48	GPIO (5V)	PF0	49	GPIO (5V)
PF1	50	GPIO (5V)	PF2	51	GPIO
PF3	52	GPIO	PF4	53	GPIO
PF5	54	GPIO	PE8	56	GPIO
PE9	57	GPIO	PE10	58	GPIO
PE11	59	GPIO	PE12	60	GPIO
PE13	61	GPIO	PE14	62	GPIO
PE15	63	GPIO	PA15	64	GPIO

**Note:**

1. GPIO with 5V tolerance are indicated by (5V).

Table 5.27. ADC0 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSA Y	BUSA X	BUSA DC0 Y	BUSA DC0 X	Bus
PF15	PF15			PF14	PB14	PB15	PB15			CH31
PF14	PF13	PF13		PF12	PB12	PB13	PB13	PB14		CH30
PF12	PF11	PF11		PF10	PB10	PB11	PB11			CH29
PF10	PF9	PF9		PF8	PB9	PB9	PB9	PB10		CH28
PF8	PF7	PF7		PF6	PB6	PB6	PB6	PB6		CH27
PF6	PF5	PF5		PF4	PB4	PB5	PB5	PB4		CH26
PF4	PF3	PF3		PF2	PB2	PB3	PB3	PB2		CH25
PF2	PF1	PF1		PF0	PB0	PB1	PB1	PB0		CH24
PF0	PE15	PE15		PE14	PA14	PA15	PA15	PA14		CH23
PE14	PE13	PE13		PE12	PA12	PA13	PA13	PA12		CH22
PE12	PE11	PE11		PE10	PA10	PA11	PA11	PA10		CH21
PE10	PE9	PE9		PE8	PA8	PA9	PA9	PA8		CH20
PE8	PE7	PE7		PE6	PA6	PA7	PA7	PA6		CH19
PE6	PE5	PE5		PE4	PA4	PA5	PA5	PA4		CH18
PE4					PA3	PA3	PA3	PA2		CH17
	PE1	PE1		PE0	PA0	PA1	PA1	PA0		CH16
PE0										CH15

Table 5.28. ADC1 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSA Y	BUSA X	BUSADC1Y	BUSADC1X	Bus
PF15	PF15			PF14	PB14	PB15	PB15			CH31
PF14	PF13	PF13		PF12	PB12	PB13	PB13	PB14		CH30
PF12	PF11	PF11		PF10	PB10	PB11	PB11			CH29
PF10	PF9	PF9		PF8	PB9	PB9	PB9	PB10		CH28
PF8	PF7	PF7		PF6	PB6	PB6	PB6	PB6		CH27
PF6	PF5	PF5		PF4	PB4	PB5	PB5	PB4		CH26
PF4	PF3	PF3		PF2	PB2	PB3	PB3	PB2		CH25
PF2	PF1	PF1		PF0	PB0	PB1	PB1	PB0		CH24
PF0	PE15	PE15		PE14	PA14	PA15	PA15	PA14		CH23
PE14	PE13	PE13		PE12	PA12	PA13	PA13	PA12		CH22
PE12	PE11	PE11		PE10	PA10	PA11	PA11	PA10		CH21
PE10	PE9	PE9		PE8	PA8	PA9	PA9	PA8		CH20
PE8	PE7	PE7		PE6	PA6	PA7	PA7	PA6		CH19
PE6	PE5	PE5		PE4	PA4	PA5	PA5	PA4		CH18
PE4					PA3	PA3	PA3	PA2		CH17
	PE1	PE1			PA1	PA1	PA1	PA0		CH16
PE0			PE0	PE0	PA0	PA0	PA0	PA0		CH15

## 8.2 BGA120 PCB Land Pattern

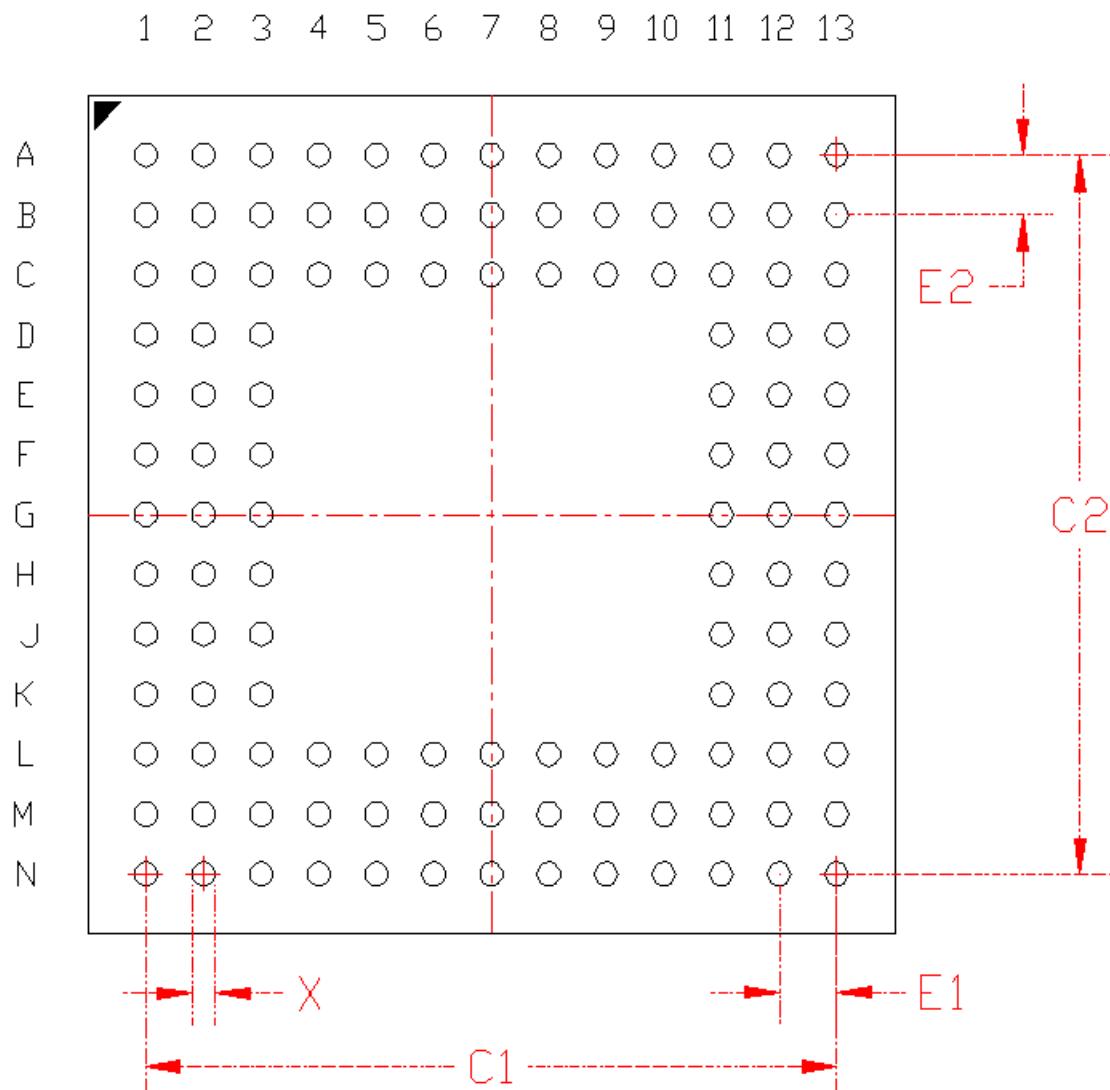


Figure 8.2. BGA120 PCB Land Pattern Drawing